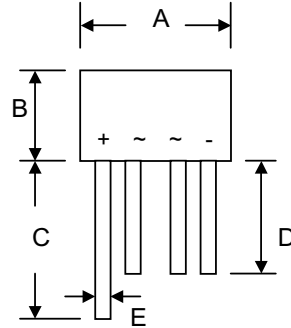


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Features

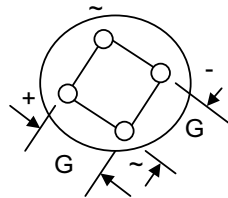
- Glass Passivated Die Construction
- Low Forward Voltage Drop
- High Current Capability
- High Reliability
- High Surge Current Capability
- Ideal for Printed Circuit Boards
- Case to Terminal Isolation Voltage 2500V
- UL Recognized File # E223064



Dim	WOB			
	Min	Max	Min	Max
A	8.60	9.10	0.339	0.358
B	5.00	5.50	0.197	0.217
C	27.9	—	1.10	—
D	25.4	—	1.00	—
E	0.71	0.81	0.028	0.032
G	4.60	5.60	0.181	0.220
	In mm		In inch	

Mechanical Data

- Case: Molded Plastic
- Terminals: Plated Leads Solderable per MIL-STD-202, Method 208
- Polarity: As Marked on Body
- Weight: 1.1 grams (approx.)
- Mounting Position: Any
- Marking: Type Number



Maximum Ratings and Electrical Characteristics @T_A=25°C unless otherwise specified

Single Phase, half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

Characteristic	Symbol	W005G	W01G	W02G	W04G	W06G	W08G	W10G	Unit
Peak Repetitive Reverse Voltage	V _{RRM}	50	100	200	400	600	800	1000	V
Working Peak Reverse Voltage	V _{RWM}								
DC Blocking Voltage	V _R								
RMS Reverse Voltage	V _{R(RMS)}	35	70	140	280	420	560	700	V
Average Rectified Output Current (Note 1) @T _A = 50°C	I _O	1.5							A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}	50							A
Forward Voltage (per element) @I _F = 1.5A	V _{FM}	1.0							V
Peak Reverse Current @T _A = 25°C At Rated DC Blocking Voltage @T _A = 100°C	I _{RM}	5.0 500							μA
Operating Temperature Range	T _J	-55 to +150							°C
Storage Temperature Range	T _{STG}	-55 to +150							°C

Note: 1. Leads maintained at ambient temperature at a distance of 9.5mm from the case.

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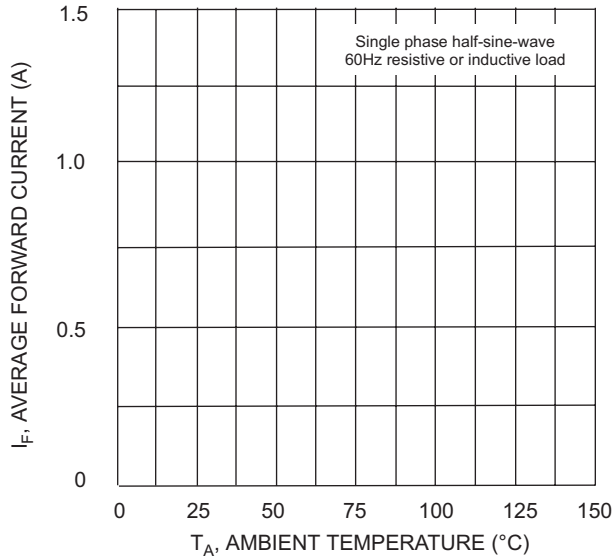


Fig. 1 Forward Current Derating Curve

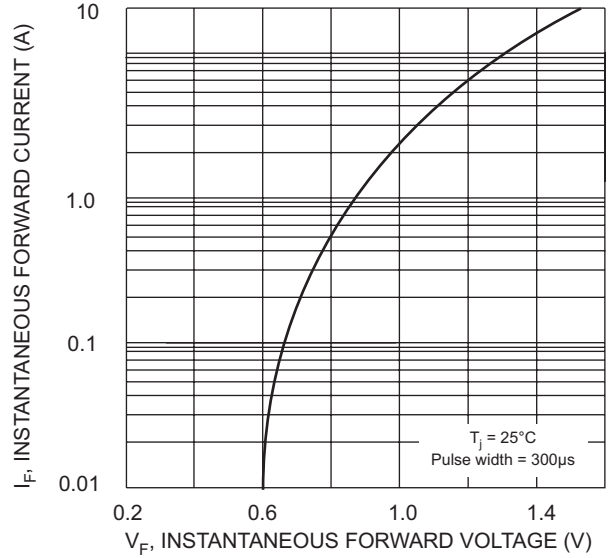


Fig. 2 Typical Forward Characteristics, per element

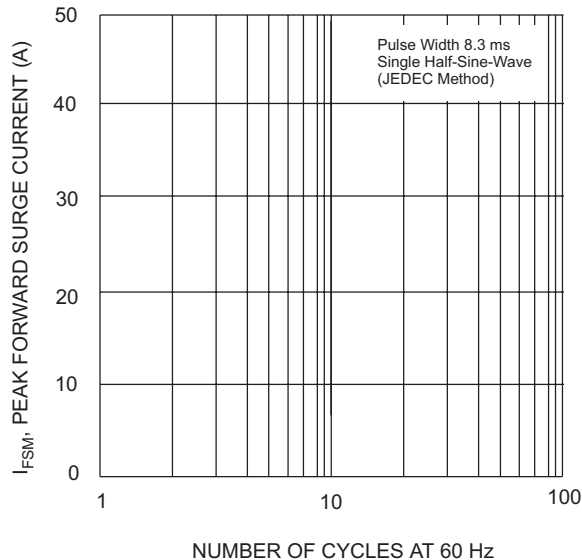


Fig. 3 Max Non-Repetitive Surge Current

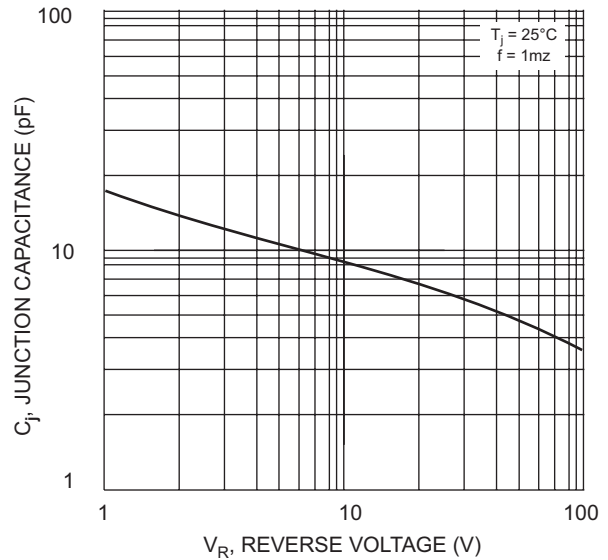


Fig. 4 Typical Junction Capacitance

TECHNICAL DATA

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